



Session Title:	[ThC1] Heterogeneous Integration
Session Date:	November 14 (Thu.), 2024
Session Time:	09:00-10:25
Session Room:	Room C (Grand Ballroom 3, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Jinsub Park (Hanyang Univ., Korea)

[ThC1-1] [Invited]

09:00-09:30

Chip-on-Wafer (CoW) Technology Utilizing Laser-Assisted Bonding with Compression (LABC) with Laser Non-Conductive Film (NCF)

Kwang-Seong Choi, Jiho Joo, Gwang-Mun Choi, Jungho Shin, Chanmi Lee, Ki-Seok Jang, Jin-Hyuk Oh, Ho-Gyeong Yun, Seok Hwan Moon, Ji Eun Jung, Gaeun Lee, and Yong-Sung Eom (ETRI, Korea)

[ThC1-2] [Invited]

09:30-10:00

Wafer Bonding for Chiplet and Logic Devices

Fumihiko Inoue (Yokohama Nat'l Univ., Korea)

[ThC1-3] [Invited]

10:00-10:25

Wafer Bonding Technology for 3D Integration from In-fab to the Advanced Package

SeungWoo Choi, SunGhil Lee, YoungWoo Park, and JaiHyung Won (Tokyo Electron Korea, Korea)